

CLAIMS:

1. A silicone resin composition for LED devices, comprising
  - 5 (A) a silicone resin having at least two alkenyl groups bonded to silicon atoms in a molecule,
  - (B) an organohydrogensilane and/or organohydrogenpolysiloxane having at least two hydrogen atoms bonded to silicon atoms in a molecule, and
  - 10 (C) an addition reaction catalyst.
2. The composition of claim 1 which is heat curable.
3. A silicone resin composition for LED devices, comprising
  - 15 (A) 100 parts by weight of a liquid or solid organopolysiloxane represented by the average compositional formula (1):

20  $R_nSiO_{(4-n)/2}$  (1)

wherein R is independently a substituted or unsubstituted monovalent hydrocarbon group, alkoxy group or hydroxyl group, 0.1 to 80 mol% of the entire R groups being alkenyl groups, and n is a positive number of  $1 \leq n < 2$ , and having a viscosity of at least 10 mPa·s at 25°C,

25 (B) 2 to 100 parts by weight of an organohydrogenpolysiloxane having at least two SiH bonds in a molecule represented by the average compositional formula (2):

30  $R'_aH_bSiO_{(4-a-b)/2}$  (2)

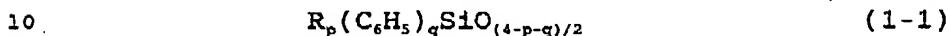
wherein R' is independently a substituted or unsubstituted monovalent hydrocarbon group excluding an aliphatic unsaturated hydrocarbon group, "a" is a positive number of 0.7 to 2.1, "b" is a positive number of 0.001 to 1.0, satisfying  $0.8 \leq a+b \leq 2.6$ , and having a viscosity of up to 1,000 mPa·s at 25°C and/or an organohydrogensilane

represented by the formula:  $R'_{c}SiH_{(4-c)}$  wherein  $R'$  is as defined above and  $c$  is 1 or 2, and

(C) a catalytic amount of an addition reaction catalyst.

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4. The composition of claim 3 wherein component (A) is a liquid or solid organopolysiloxane represented by the average compositional formula (1-1):



wherein  $R$  is independently a substituted or unsubstituted monovalent hydrocarbon group, alkoxy group or hydroxyl group, 0.1 to 80 mol% of the entire  $R$  groups being alkenyl groups, 15 and  $p$  and  $q$  are positive numbers satisfying  $1 \leq p+q < 2$  and  $0.20 \leq q/(p+q) \leq 0.95$ , and having a viscosity of at least 100 mPa·s at 25°C.

5. The composition of claim 3 wherein component (B) is an 20 organohydrogenpolysiloxane of the compositional formula (2) wherein phenyl groups comprise at least 5 mol% of the entire  $R'$  and  $H$ .

6. The composition of claim 3 wherein component (B) is a 25 mixture of an organohydrogenpolysiloxane of the compositional formula (2) wherein phenyl groups comprise less than 15 mol% of the entire  $R'$  and  $H$  and an organohydrogenpolysiloxane of the compositional formula (2) wherein phenyl groups comprise at least 15 mol% of the entire  $R'$  and  $H$  in a weight ratio 30 between 1:9 and 9:1.